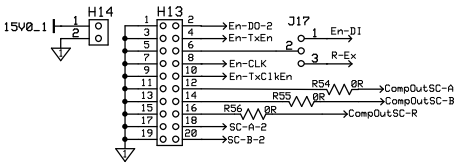


**Processor Section**  
 (next page)

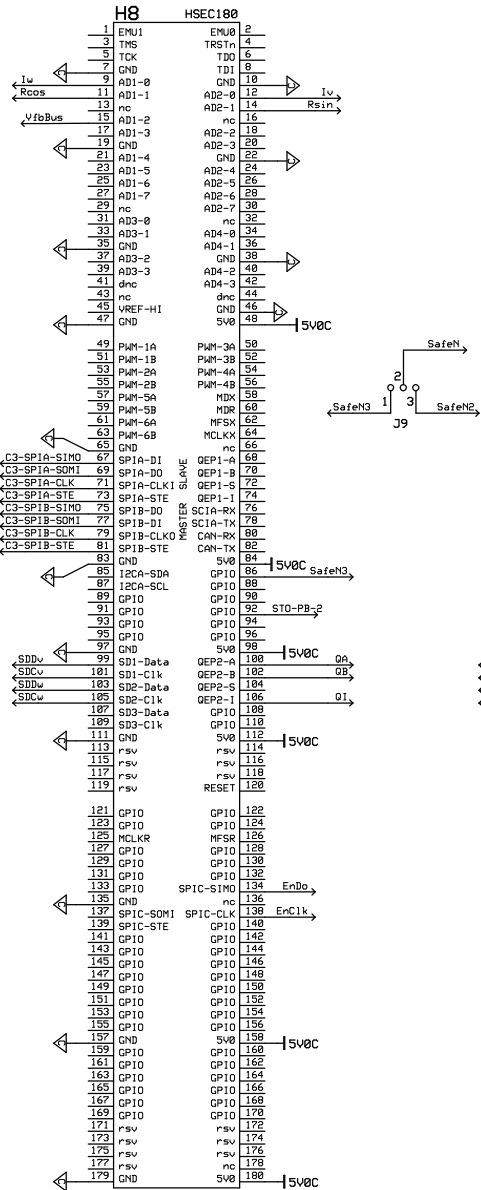
Industrial Motor Position Sensor Header



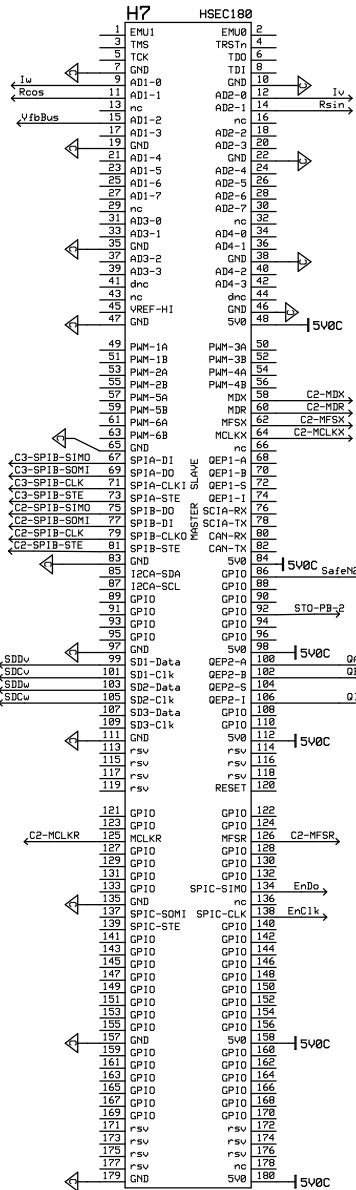
<b>Texas Instruments</b>		
TIDM-SERVODRIVE		
Industrial Drive Development Kit		
Power and Interface		
<b>IDDK</b>	[R2.2]	Page 1 of 2
	01/26/2015	

Rev History:  
 R2.1 ----> R2.2  
 Encoder Header H3, H4 and H6 pins reassigned  
 5V-Enc from [Endat/Biss] connected to [SinCos] also

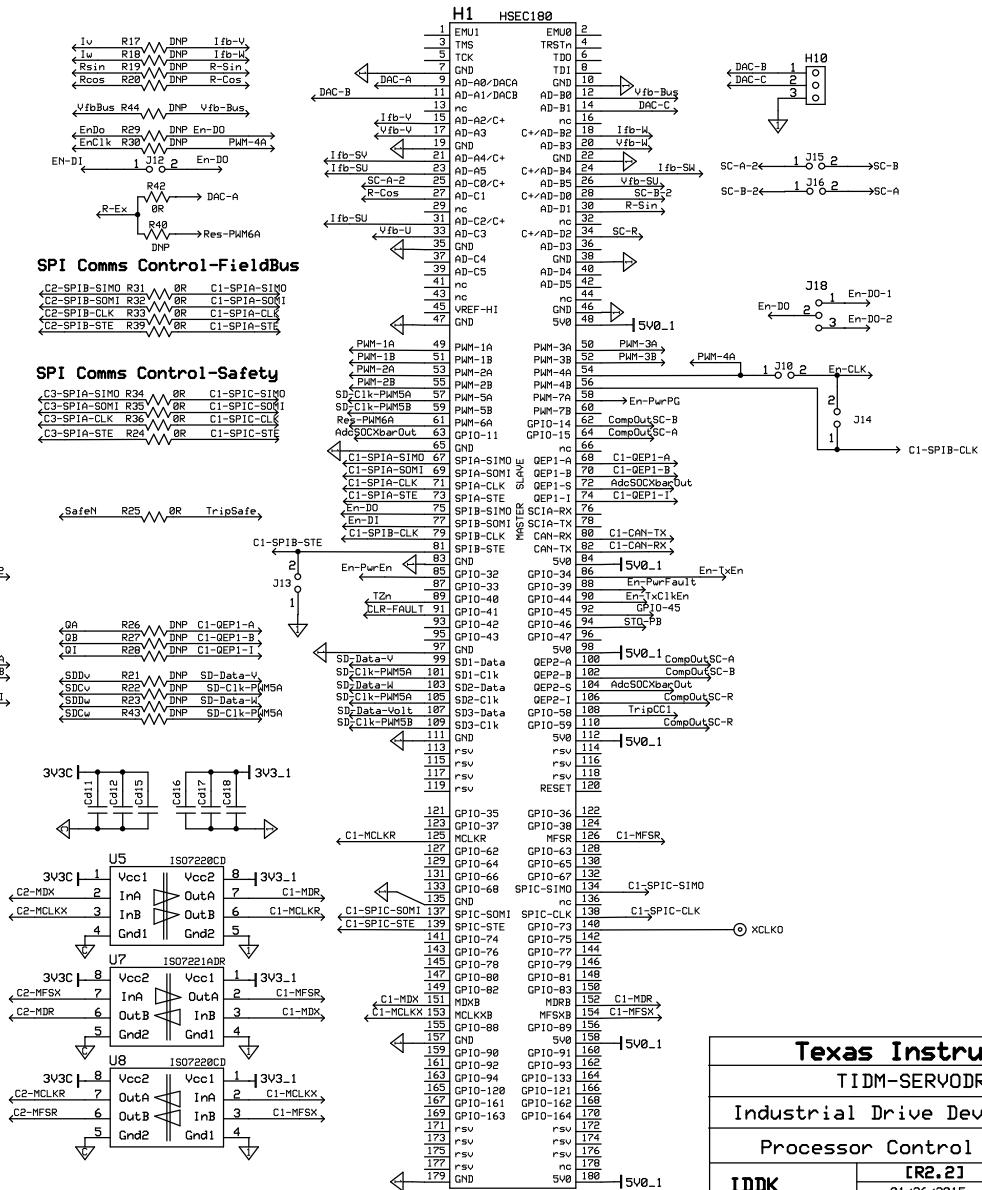
**Control Card #3 (C3)  
Safety Module**

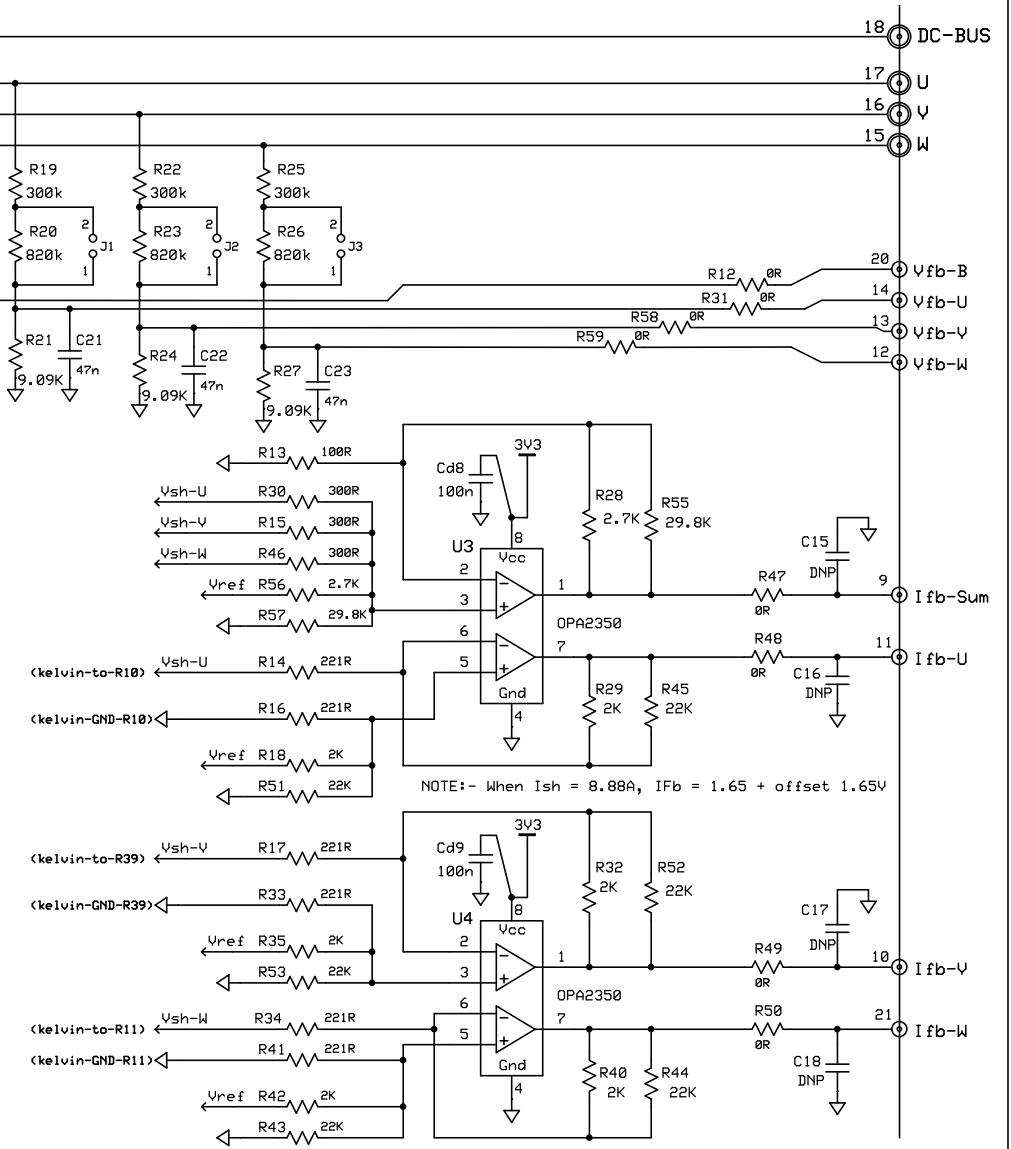
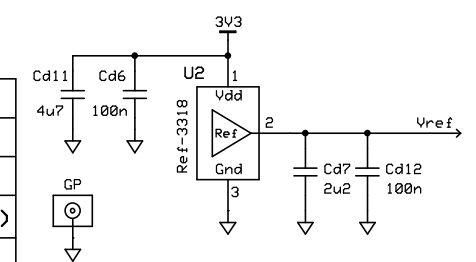
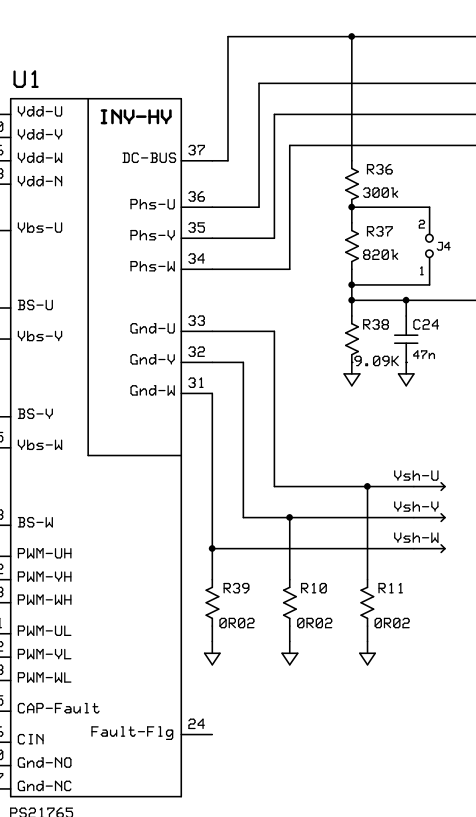
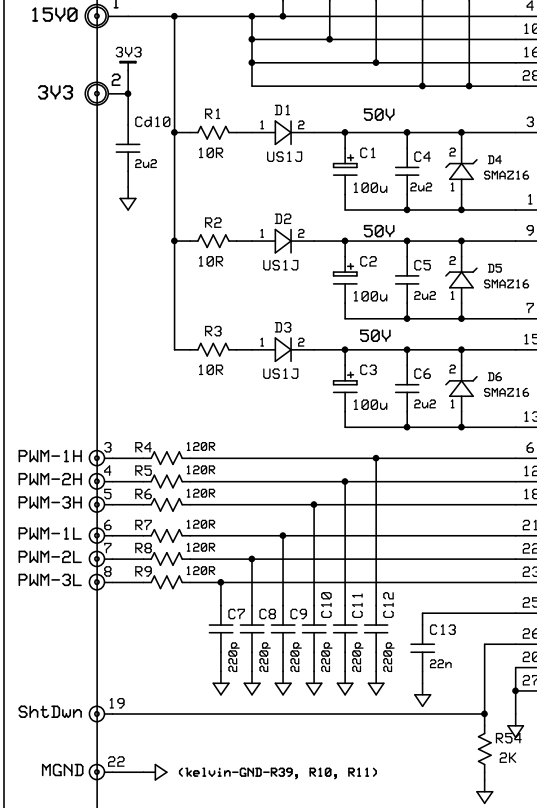
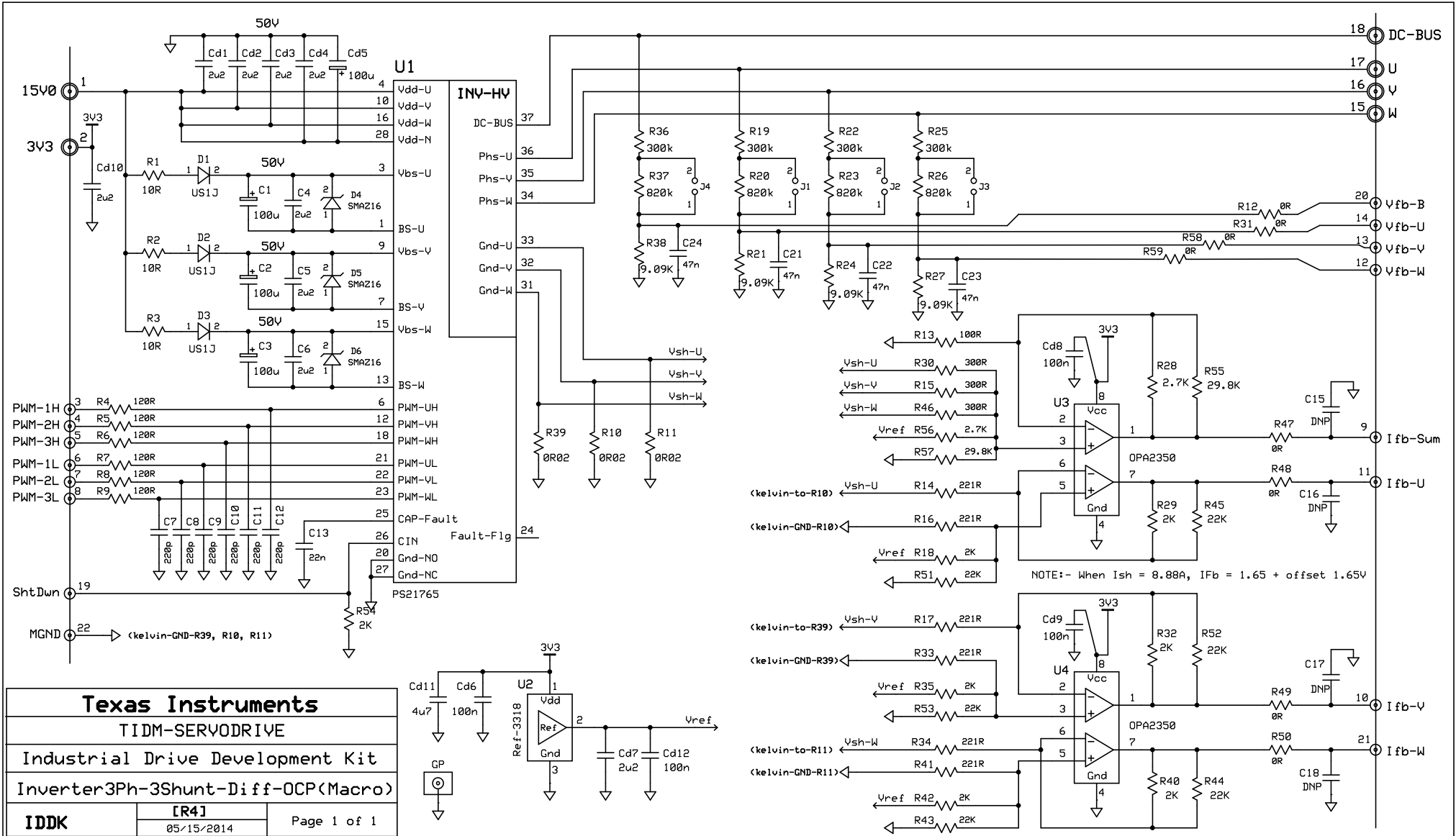


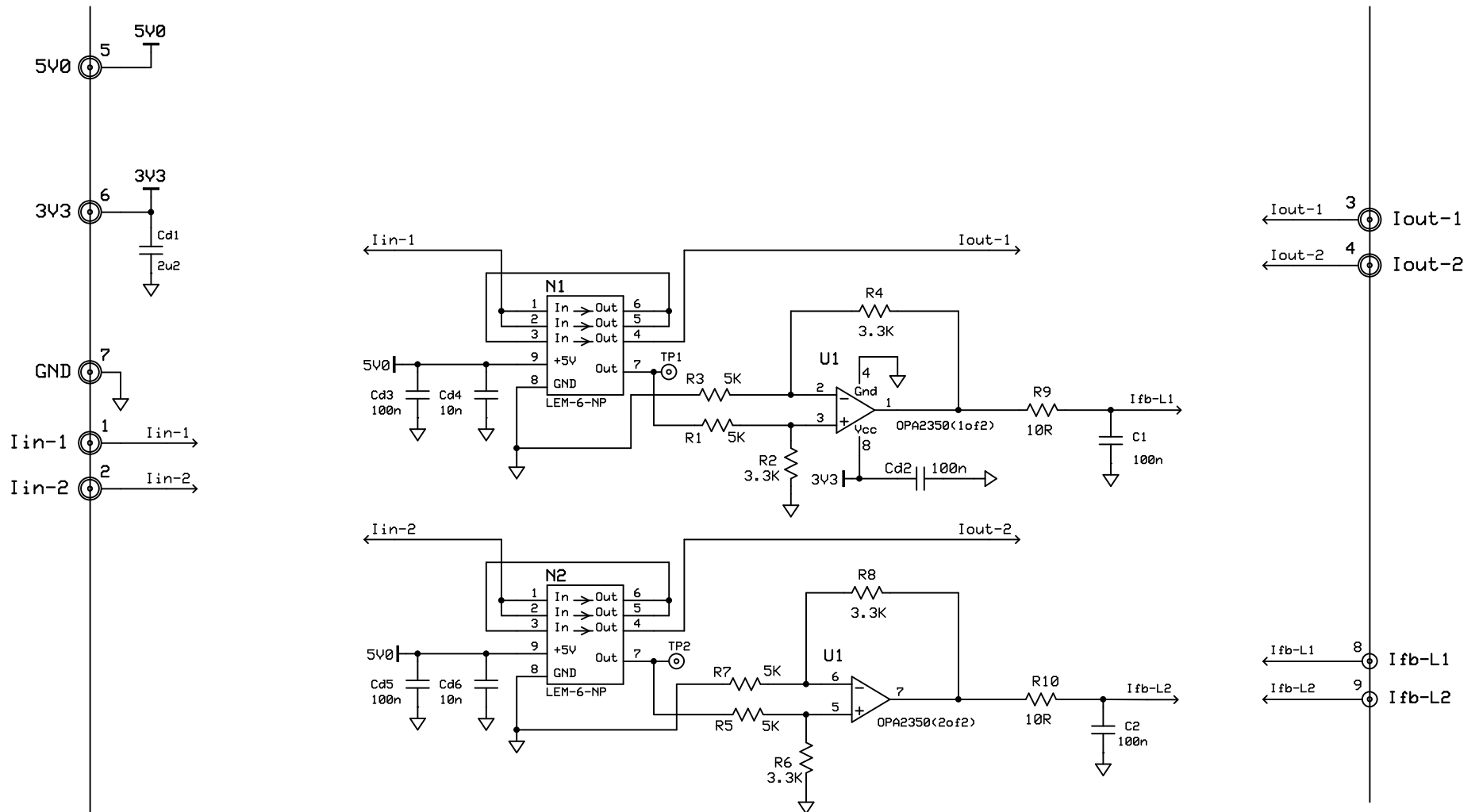
**Control Card #2 (C2)  
FieldBus + Applications**



**Control Card #1 (C1)  
Control**







Symbol

MLEM-CurrentSense-2phs-R2

1	Iin-1	Iout-1	3
2	Iin-2	Iout-2	4
5	5V0	Ifb-L1	8
7	GND	Ifb-L2	9
6	3V3		

**Texas Instruments**

TIDM-SERVODRIVE

Industrial Drive Development Kit

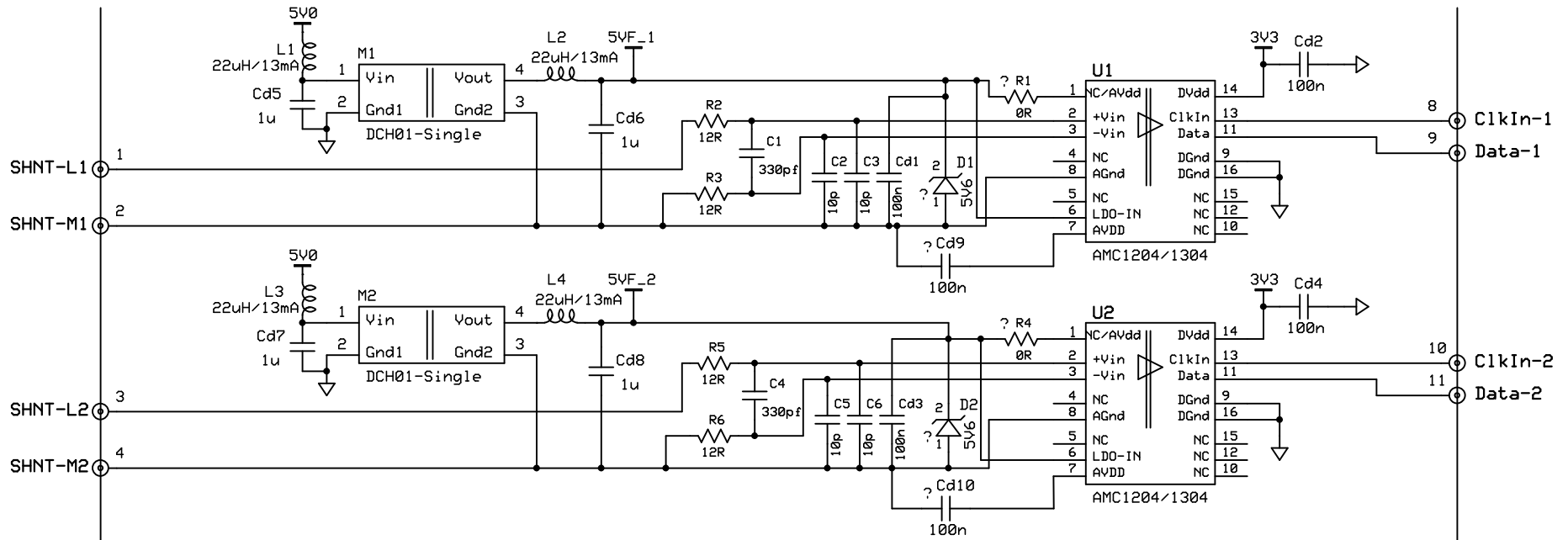
LEM CurrentSense - 2 phase

IDDK

[R1]

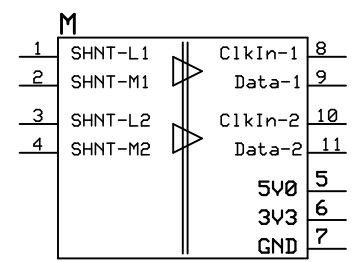
21/04/2014

Page 1 of 1

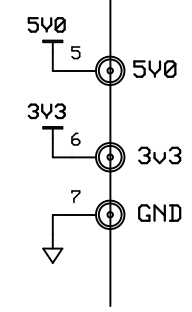


NOTE :-  
 For AMC1204: Cd9,Cd10,D1,D2 are DNP  
 For AMC1304: R1,R4,D1,D2 are DNP

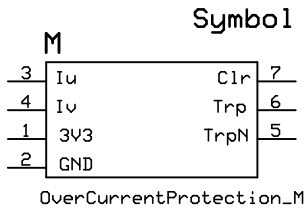
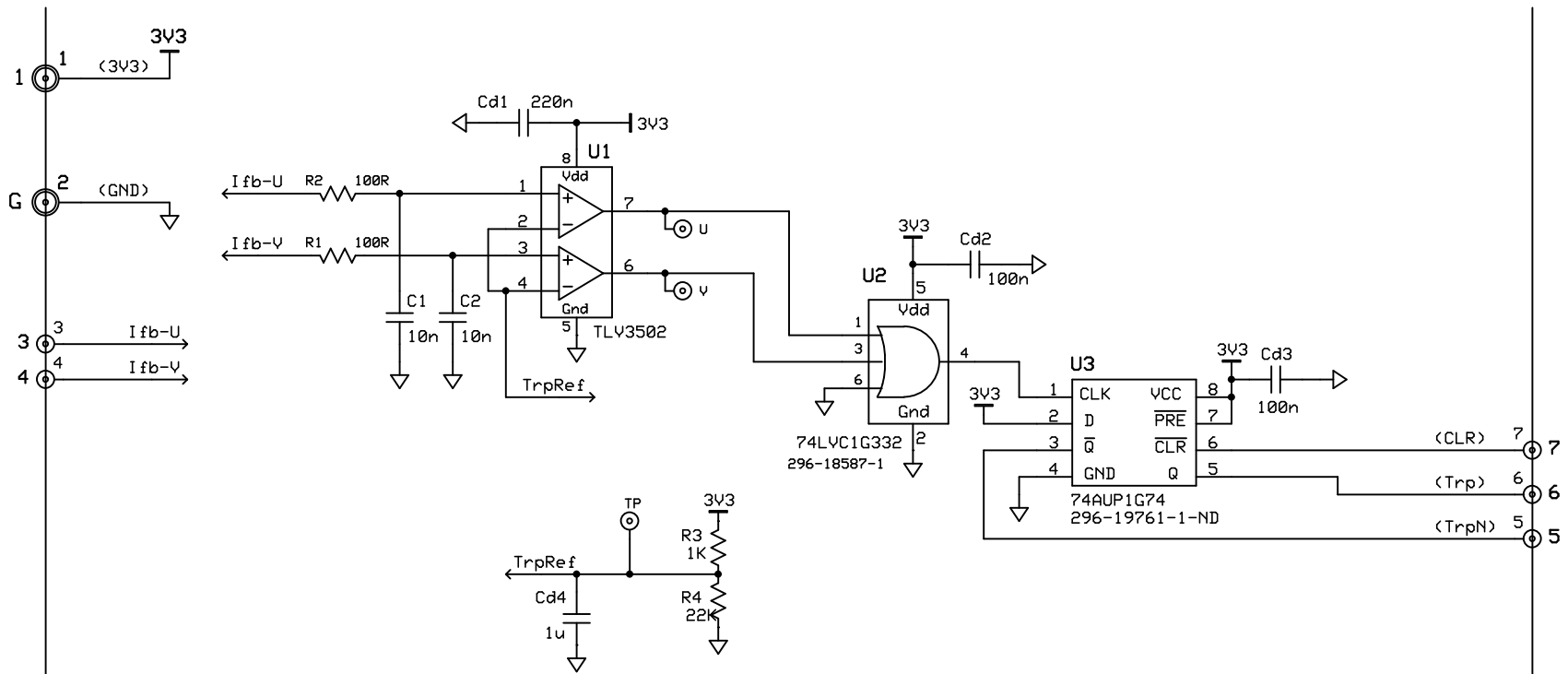
Symbol

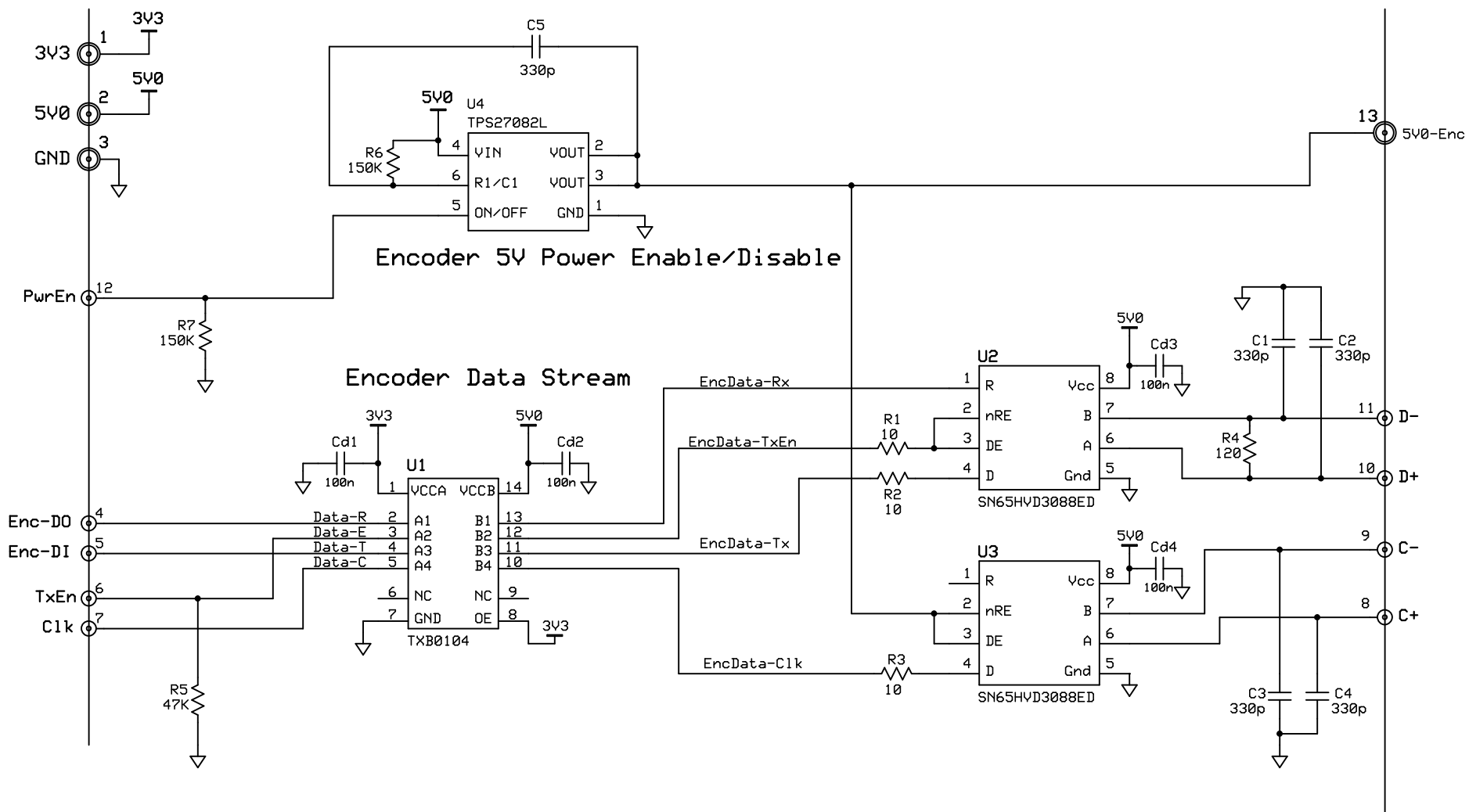


SD-CurrentSense-2ph-R3



<b>Texas Instruments</b>		
TIDM-SERVODRIVE		
Industrial Drive Development Kit		
SD Current Sense - 2 phase		
<b>IDDK</b>	<b>[R1]</b>	Page 1 of 1
	05/13/2014	





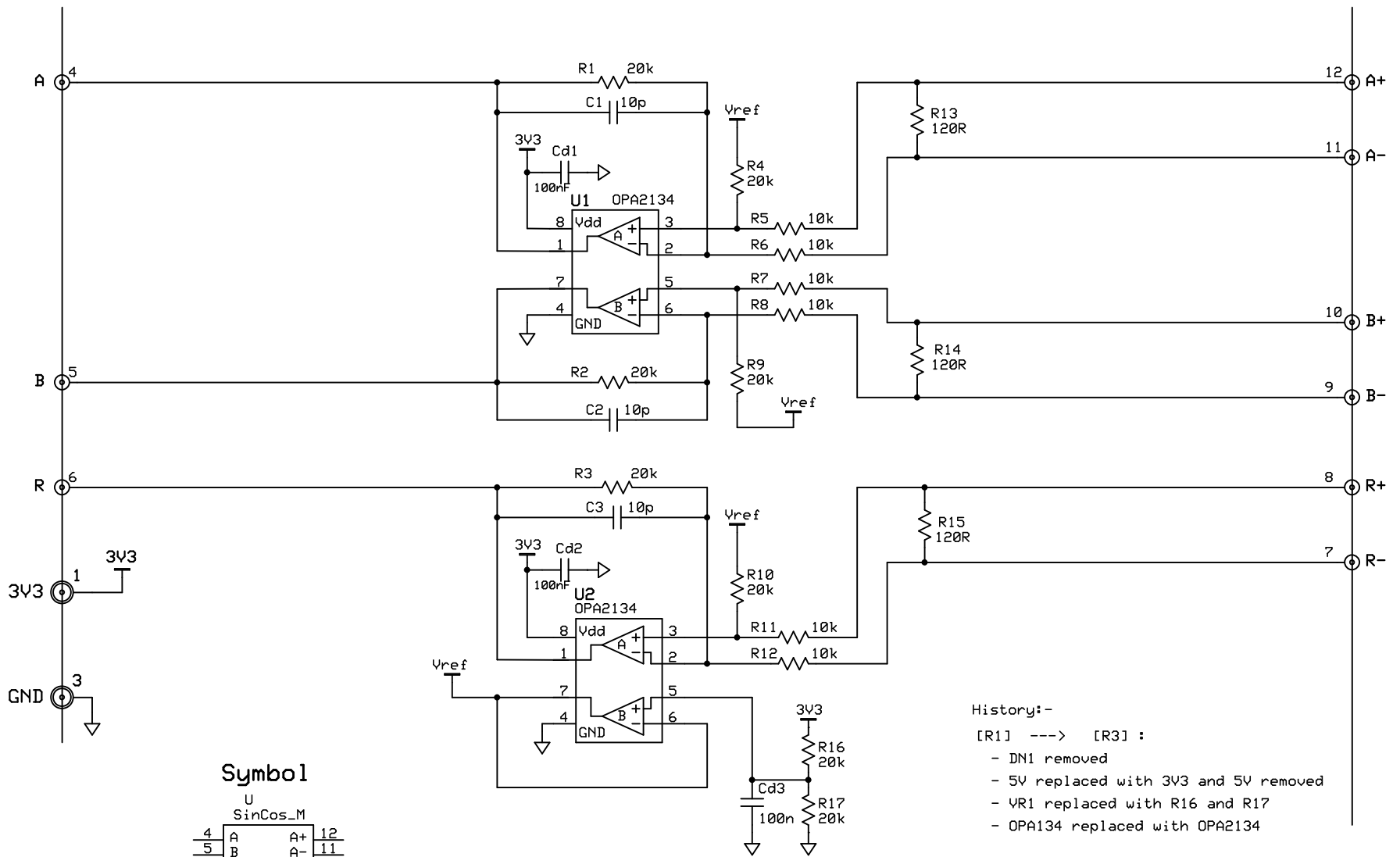
Encoder 5V Power Enable/Disable

Encoder Data Stream

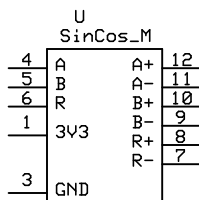
Symbol

U EnDat-BiSS_M			
4	Enc-DO	Data-	11
5	Enc-DI	Data+	10
6	Enc-TxEn	Clk-	9
7	Enc-C1k	Clk+	8
12	EncPwrEn		
1	3V3	5V0-Enc	13
2	5V0	GND	3

<b>Texas Instruments</b>		
TIDM-SERVODRIIVE		
Industrial Drive Development Kit		
Endat/BiSS Interface		
<b>IDDK</b>	[R1]	Page 1 of 1
	05/12/2014	



**Symbol**



**History:-**

[R1] ---> [R3] :

- DN1 removed
- 5V replaced with 3V3 and 5V removed
- VR1 replaced with R16 and R17
- OPA134 replaced with OPA2134

**Texas Instruments**

TIDM-SERVODRIVE

Industrial Drive Development Kit

SinCos Interface

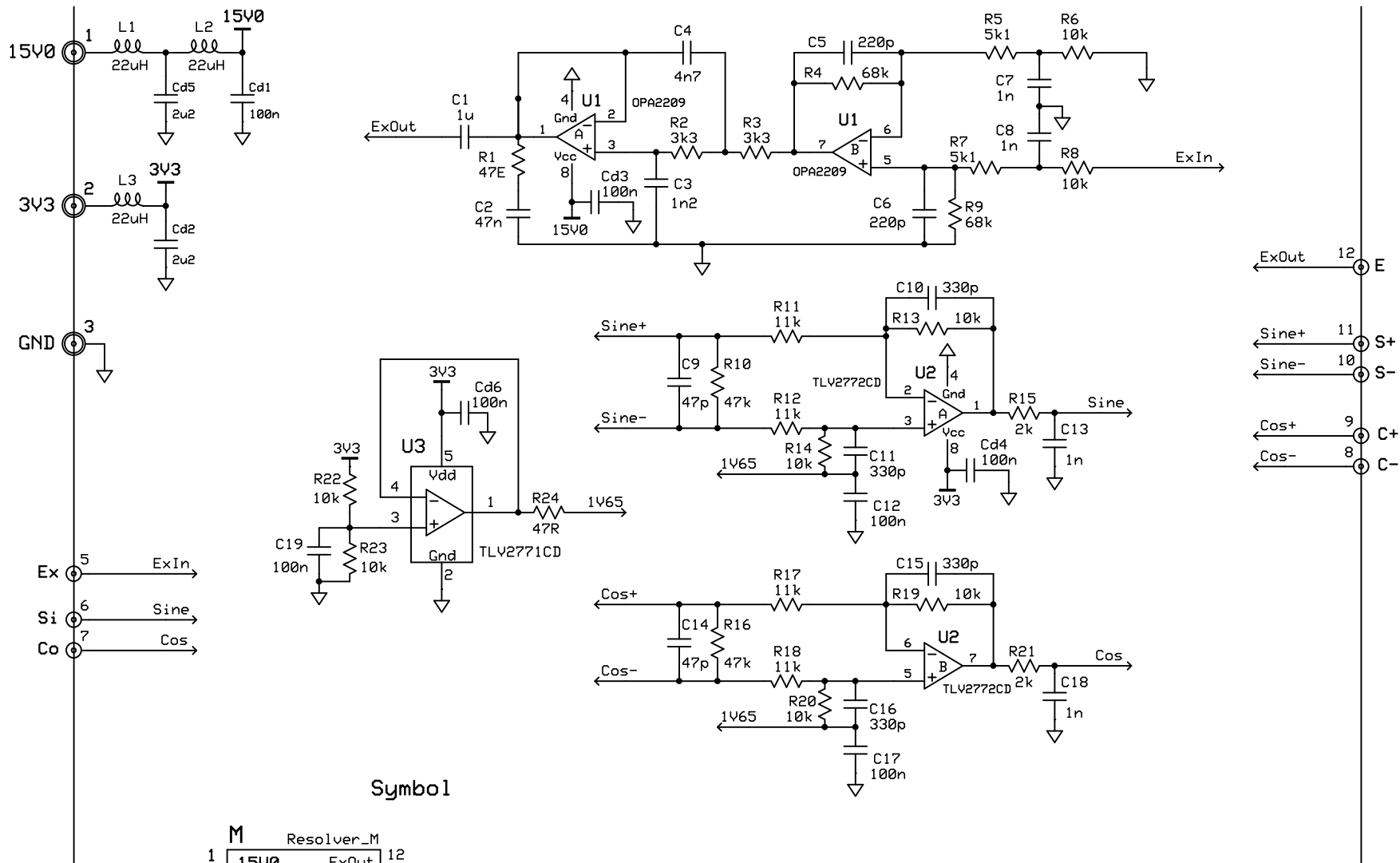
IDDK

[R1]

01/06/2015

Page 1 of 1



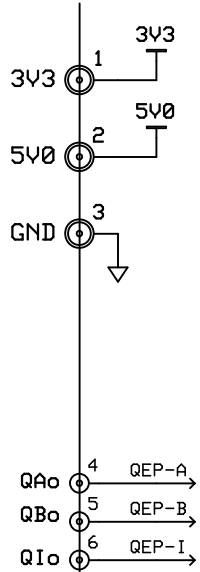


Symbol

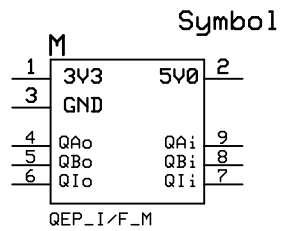
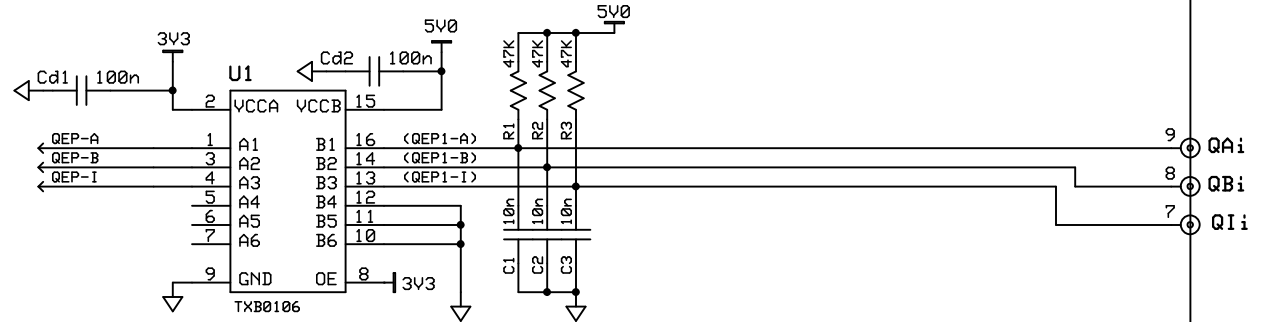
M	Resolver_M		
1	15V0	ExOut	12
2	3V3	Sine+	11
5	ExIn	Sine-	10
6	Sine	Cos+	9
7	Cos	Cos-	8
3	GND		

NOTE:- All caps rated 25V

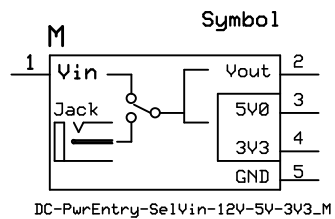
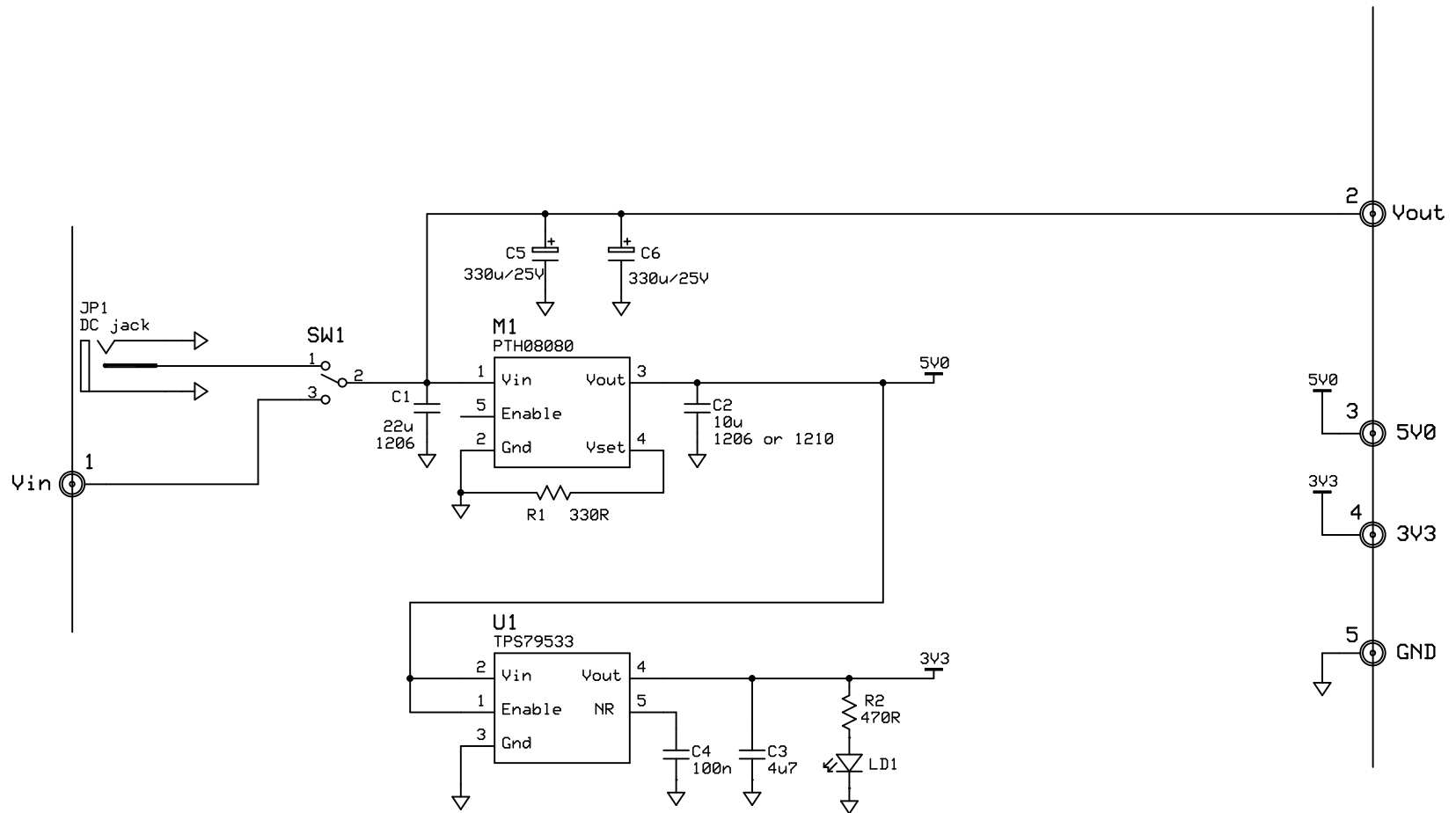
<b>Texas Instruments</b>		
TIDM-SERVODRIVE		
Industrial Drive Development Kit		
Resolver Interface		
<b>IDDK</b>	<b>[R1]</b>	Page 1 of 1
	07/15/2013	



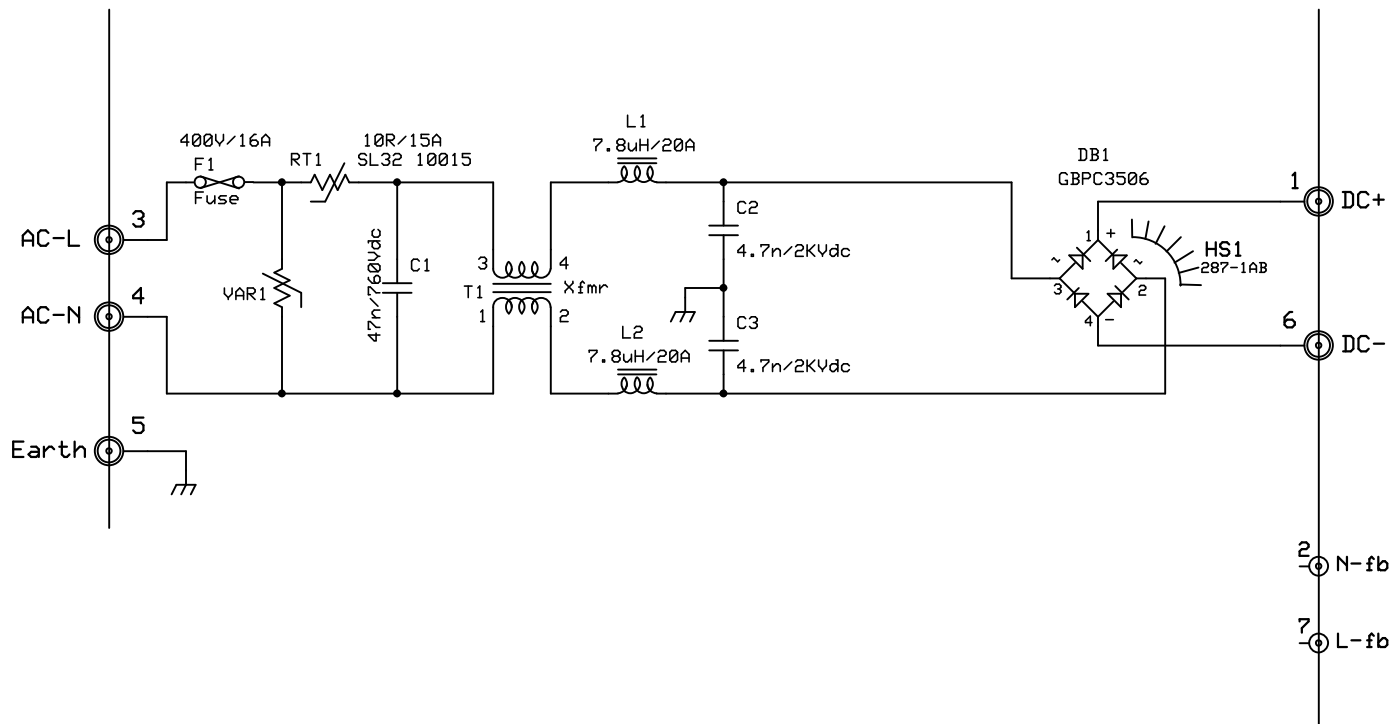
### Quadrature Encoder Interface



<b>Texas Instruments</b>		
TIDM-SERVODRIIVE		
Industrial Drive Development Kit		
QEP Interface		
<b>IDDK</b>	[R1]	Page 1 of 1
	07/17/2013	

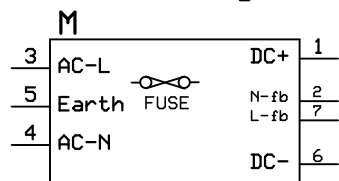


<b>Texas Instruments</b>		
TIDM-SERVODRIVE		
Industrial Drive Development Kit		
DC-PwrEntry-SelVin-12V-5V-3V3_M		
<b>IDDK</b>	[R1]	Page 1 of 1
	07/19/2013	



NOTE:-  
Pins 2 and 4 are NC

Symbol



AC-PwrEntry-Filter-ret-LNMeas

<b>Texas Instruments</b>		
TIDM-SERVODRIVE		
Industrial Drive Development Kit		
AC-Power - Filter		
<b>IDDK</b>	[R1]	Page 1 of 1
	08/17/2011	

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